

PCN-2014-541

Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia (SCM) to ANST Wuxi CHINA for the CS42L51-CNZ(R), CS42L51-DNZ(R), CS53L21-CNZ(R) and CS53L21-DNZ(R) components

Process/Product Change Notification (Reference Advance PCN-2014-522)

Date: June 2014

Dear Customer:

This is a Final Announcement of the Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia to ANST Wuxi CHINA for the CS42L51-CNZ(R), CS42L51-DNZ(R), CS43L21-CNZ(R), CS53L21-CNZ(R) and CS53L21-DNZ(R) components that are currently offered by Cirrus Logic. This Final announcement is a follow on to the Advance PCN notification communicated to all customers in February of this calendar year 2014. The details of this Assembly Site Transfer are outlined on the following pages.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the lifetime buy offering/discontinuance plan.

The described change(s) within this PCN will not be realized or take effect any earlier than **60** days from the date of this notification, unless a customer agreement has been reached on an earlier implementation of the change or successful completion of the defined qualification has been realized.

Please note that the notification period has been reduced from 90 days to 60 days as the SCM site recently informed Cirrus that the closure date has been moved forward from December 31^{st} , 2014 to September 30^{th} , 2014. Cirrus has no control over any changes to the site closure date.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

PCN Coordinator Cirrus Logic Corporate Quality Phone: +1(512) 851-4000

Attachment: 1

Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

| PCN Number: | | | 201 | 014-541 PC | | | PC | PCN Date: | | | June 2014 | |
|-------------------------------------|---|------|---|------------------|----------|-------------------------------------|-------------|------------|--------------|-----------|----------------------|--|
| Title: | Assembly Site Transfer from StatsChipPac Kuala Lumpur, Malaysia to ANST Wuxi CHINA for the CS42L51-CNZ(R), CS42L51-DNZ(R), CS43L21-CNZ(R), CS53L21-CNZ(R) and CS53L21-DNZ(R) components | | | | | | | | | | | |
| Customer Local Field Representa | | | | | | Phone: (512) 851-40 | | | | Dept: | Corporate Quality | |
| Proposed 1 st Ship Date: | | | : | Augu | ıst 2014 | Estimated Sample Availability date: | | | | June 2014 | | |
| Change Type: | | | Assembly Site Transfer to an existing Qual Location: Change Type = Major | | | | Qua | lified Cii | rrus Log | ic Site | | |
| Assembly Site | | | | Assembly Process | | | \boxtimes | Assen | ıbly Ma | terials | | |
| □ Design □ | | | Electrical Specification | | | | Mecha | nical S | pecification | | | |
| ☐ Test Site ☐ | | | Packing/Shipping/Labeling | | | | Test P | rocess | | | | |
| | | Wafe | Wafer Bump Material | | | | Wafer | Bump | Process | | | |
| ☐ Wafer Fab Site ☐ | | | Wafer Fab Materials | | | | Wafer | Fab Pr | ocess | | | |

| PCN | Details |
|------------|----------------|
| | |

Description of Change:

Cirrus Logic's package Assembly and Test Supplier, StatsChipPac, has announced their site in Kuala Lumpur, Malaysia will close by September 30th, 2014.

Cirrus Logic is qualifying and will move these products to the existing qualified subcontractor (ANST) site location in Wuxi CHINA.

Below you will find an outline of the described changes for these components:

CS42L51-CNZ(R), CS42L51-DNZ(R), CS43L21-CNZ(R), CS53L21-CNZ(R) and CS53L21-DNZ(R)

• Assembly Site Change:

From: StatsChipPac Kuala Lumpur, Malaysia → To: ANST Wuxi CHINA

PackMark COO Symbolization:

From: MYS → To: CHN

Mold Compound:

From: Sumitomo EME-G770 → To: Hitachi CEL-9240HF

Reason for Change:

Cirrus Logic's package Assembly and Test Supplier, StatsChipPac, has announced their site in Kuala Lumpur, Malaysia will close by September 30th, 2014.

Cirrus Logic is qualifying and will move these products to the existing qualified subcontractor (ANST) site location in Wuxi CHINA.

Special Note:

As a full services supplier and in order to ensure continuity of supply as well as sustain quality an accelerated timeframe has been established for the full transfer of said product no later than September 30th, 2014.

Earlier production level material may be available from the qualified subcontractor (ANST) site location in Wuxi CHINA, but shipment(s) from Cirrus Logic are contingent on successful completion of the designated site transfer qualification.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Anticipated No Adverse Impact to the Quality & Reliability of said product; as Transfer Site is an existing Cirrus Logic qualified subcontractor (ANST) site (Wuxi CHINA) and considered low risk.

| Product Affected: | 🛛 🖾 Table I |
|--------------------------|-------------|
|--------------------------|-------------|

| | Customer Material Part Number | Cirrus Logic Part Number |
|-----------|--------------------------------------|--------------------------|
| Device 1: | | CS42L51-CNZ(R) |
| Device 2: | | CS42L51-DNZ(R) |
| Device 3: | | CS43L21-CNZ(R) |
| Device 4: | | CS53L21-CNZ(R) |
| Device 5: | | CS53L21-DNZ(R) |

Changes to product identification resulting from this PCN:

The Cirrus Logic component symbolization on the external face of the device reflects the designated Country Of Origin.

Below you will find a representative example:

Our part: CS42L51-CNZ(R), CS42L51-DNZ(R), CS43L21-CNZ(R), CS53L21-CNZ(R) and CS53L21-DNZ(R)

Mark format: **234** Mark change:

Assembly vendor = None (not shown on mark)
 COO = changing From: MYS → TO: CHN

Line 1: Country Of Origin (COO)

Line 2: Logo Line

Line 3: Part Number (6 spaces max.) Line 4: Package Mark (6 spaces max.)



With the Site Transfer to ANST Wuxi CHINA, the material will receive the appropriate designation for the Country Of Origin.

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

| released technical specifications. | | | | | | | | |
|------------------------------------|--|------------|--|----------|-----------|--|--|--|
| Qualification Schedule: | Start: | March 2014 | | End: | July 2014 | | | |
| Qualification Device Constr | Qualification Device Construction Details: | | | | | | | |
| | Device 1 | | | Device 2 | | | | |
| Part Number(s): | CS42L51-CNZ(R), CS42L51- DNZ(R), CS43L21-CNZ(R), CS53L21-CNZ(R) and CS53L21- DNZ(R) | | | | | | | |
| Wafer Fab Site: | YF | | | | | | | |
| Wafer Technology: | 0.25 | | | | | | | |
| Die Size: | 6.15 mm | | | | | | | |
| Assembly Site: | ANST Wuxi CHINA | | | | | | | |
| Package Type/Code: | 32QFN5Z 5x5 | | | | | | | |
| Moisture Level: | MSL (Moisture Sensitivity Level) 3 | | | | | | | |
| Package Pins: | 32 NL QFN | | | | | | | |
| Lead Frame Material: | Cu (Copper) | | | | | | | |
| Mold Compound Supplier: | CEL-9240HF Hitachi | | | | | | | |
| Lead Finish: | Matte Sn Plate | | | | | | | |
| Die Attach Material | Ablebond 82 | 90 | | | | | | |

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0.8mil Au (Gold)

Wire Diameter:

Wire Base Metal:

The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

CS42L51-DNZ(R) Qualification

| CS42L51-DNZ(R) Qualification: Plan Test Results | | | | | | | |
|--|----------------------------|---|----------------------------|--|--|--|--|
| Reliability Test | | | Sample Size (PASS/FAIL) | | | | |
| Pre-Conditioning | JEDEC J-STD-020A | MSL3 / 260°C (1 Lot) | 231 / 0 | | | | |
| BHAST (Biased HAST) | JESD22 A101 | 130C/85%RH/96 hrs (BHAST) Read Point (96Hrs) (1 Lot) | 77 / 0 | | | | |
| Temperature Cycle | JESD22 A104 | -65°C to +150°C for 500 cycles (1 Lots) | 77 / 0 | | | | |
| WBS (Wire Bond Shear) | JESD22 B116 | Paragraph 4 (Procedure) (1 Lot) | 5 units / lot | | | | |
| WBP (Wire Bond Pull) | MIL-STD-883 Method 2011 | Paragraph 3 (Procedure) (1 Lot) | 5 units / lot | | | | |
| SD (Solderability) | JESD22 B102 | 93°C / 8 hr steam age before SD (1 Lot) | 15 units / lot | | | | |
| PD (Physical Dimensions) | JESD22 B100 + B108 | Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lot) | 20 / 0 | | | | |
| ED (Electrical Distribution) | JESD86 | Parametric limits per datasheet or user spec Designed for -40°C to +105°C (1 Lot) | 30 / 0 | | | | |
| HTSL (High Temperature Storage Life) | JESD22 A103 | 150°C for 1000 hrs (1 Lot) | 45 / 0 | | | | |
| | | | | | | | |

Notes:

- Qualification tests "pass" on zero fails for each test
- CS42L51-DNZ(R) serves as the QBS (Qualification By Similarity) Vehicle for CS42L51-CNZ(R), CS43L21-CNZ(R), CS53L21-CNZ(R) and CS53L21-DNZ(R)